

Connector, SIM/SAM**DESIGN OBJECTIVES**

The product described in this document has not been fully tested to ensure conformance to the requirements outlined below. Therefore AMP* Incorporated makes no representation or warranty, express or implied, that the product will comply with these requirements. Further, AMP Incorporated may change these requirements based on the results of additional testing and evaluation. Contact AMP Engineering for further details.

1. SCOPE**1.1. Content**

This specification covers performance, tests and quality requirements for the AMP* Subscriber Identity Module/Security Access Module (SIM/SAM) connector which accepts MICROSIM® GSM cards meeting GSM 11.11 specifications. This connector consists of a card retaining pivoting lid with a rotating locking feature and an optional card detection switch. The connector is designed for surface mount technology and is available in 6 position, 6 position with switch, and 8 position sizes.

1.2. Qualification

When tests are performed on the subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

2. APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1. AMP Documents

- A. 109-1: General Requirements for Test Specifications
- B. 109 Series: Test Specifications as indicated in Figure 1
- C. Corporate Bulletin 401-76: Cross-reference between AMP Test Specifications and Military or Commercial Documents
- D. 114- : Application Specification
- E. 501- : Qualification Test Report

3. REQUIREMENTS**3.1. Design and Construction**

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. Materials

- A. Base: Thermoplastic
- B. Contact: Phosphor bronze with tin-lead plating on solder tail, gold plating on interface area, all over nickel underplating
- C. Lid: Thermoplastic

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3.3. Ratings

- A. Voltage: 30 vac
- B. Current: Signal application only
- C. Temperature: -40 to 90°C

3.4. Performance and Test Description

Product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1. Unless otherwise specified, all tests shall be performed at ambient environmental conditions per AMP Specification 109-1.

3.5. Test Requirements and Procedures Summary

Test Description	Requirement	Procedure
Examination of product.	Meets requirements of product drawing and AMP Spec 114-_____.	Visual, dimensional and functional per applicable quality inspection plan.
ELECTRICAL		
Termination resistance.	100 milliohms maximum.	AMP Spec 109-6-1. Subject mated contacts assembled in housing to 50 mv maximum open circuit at 100 ma maximum. See Figure 3.
Insulation resistance.	1000 megohms minimum.	AMP Spec 109-28-4. Test across opposite contacts of mated samples.
Dielectric withstanding voltage.	250 vac at sea level for switch contacts. 750 vac at sea level for data contacts. 1 minute hold with no breakdown or flashover.	AMP Spec 109-29-1. Test across opposite contacts of mated samples.
MECHANICAL		
Solderability.	Solderable area shall have minimum of 95% solder coverage.	AMP Spec 109-11-1. Subject contacts to solderability.
Vibration, random.	No discontinuities of 1 microsecond or longer duration. See Note.	AMP Spec 109-21-7, Condition B, Level C. Subject mated samples to 5-500 Hz. 15 minutes in each of 3 mutually perpendicular planes. See Figure 4.

Figure 1 (cont)

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Test Description	Requirement	Procedure
Mechanical shock, specified pulse.	No discontinuities of 1 microsecond or longer duration. See Note.	AMP Spec 109-26-1, except 10 G's. Subject mated samples to 10 G's half-sine shock pulses of 11 milliseconds duration. 3 shocks in each direction applied along 3 mutually perpendicular planes, 18 total shocks. See Figure 4.
Durability.	See Note.	AMP Spec 109-27. Mate and unmate samples with fabricated GSM test cards for 10000 cycles.

ENVIRONMENTAL

Thermal shock.	See Note.	AMP Spec 109-22. Subject mated samples to 5 cycles between -40 and 90°C.
Humidity-temperature cycling.	See Note.	AMP Spec 109-23-3, Condition B. Subject mated samples to 10 cycles between 25 and 65°C at 95% RH.
Temperature life.	See Note.	AMP Spec 109-43. Subject mated samples to temperature life at 70°C for 1000 hours.
Mixed flowing gas.	See Note.	AMP Spec 109-85-2. Subject mated samples to environmental class II for 14 days.

NOTE

Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence shown in Figure 2.

Figure 1 (end)

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3.6. Product Qualification and Requalification Test Sequence

Test or Examination	Test Group (a)				
	1	2	3	4	5
	Test Sequence (b)				
Examination of product	1,7	1,5	1,5	1,8	1,3
Termination resistance	2,6	2,4	2,4		
Insulation resistance				2,6	
Dielectric withstanding voltage				3,7	
Solderability					2
Vibration	4(c)				
Physical shock	5				
Durability	3				
Thermal shock				4	
Humidity-temperature cycling				5	
Temperature life		3(d)			
Mixed flowing gas			3(d)		

NOTE

- (a) See Para 4.1.A.
 (b) Numbers indicate sequence in which tests are performed.
 (c) Samples mated with cards fabricated to meet GSM 11.11 specifications.
 (d) Precondition samples with 10 cycles durability.

Figure 2

4. QUALITY ASSURANCE PROVISIONS

4.1. Qualification Testing

A. Sample Selection

Samples shall be prepared in accordance with applicable Instruction Sheets and shall be selected at random from current production. Test groups 1, 2, 3 and 5 shall each consist of a minimum of 5 samples soldered to printed circuit boards. Test group 4 shall consist of a minimum of 5 unmounted samples.

B. Test Sequence

Qualification inspection shall be verified by testing samples as specified in Figure 2.

4.2. Requalification Testing

If changes significantly affecting form, fit or function are made to the product or manufacturing process, product assurance shall coordinate requalification testing, consisting of all or part of the original testing sequence as determined by development/product, quality and reliability engineering.

4.3. Acceptance

Acceptance is based on verification that the product meets the requirements of Figure 1. Failures attributed to equipment, test setup or operator deficiencies shall not disqualify the product. When product failure occurs, corrective action shall be taken and samples resubmitted for qualification. Testing to confirm corrective action is required before resubmittal.

4.4. Quality Conformance Inspection

The applicable AMP quality inspection plan shall specify the sampling acceptable quality level to be used. Dimensional and functional requirements shall be in accordance with the applicable product drawing and this specification.

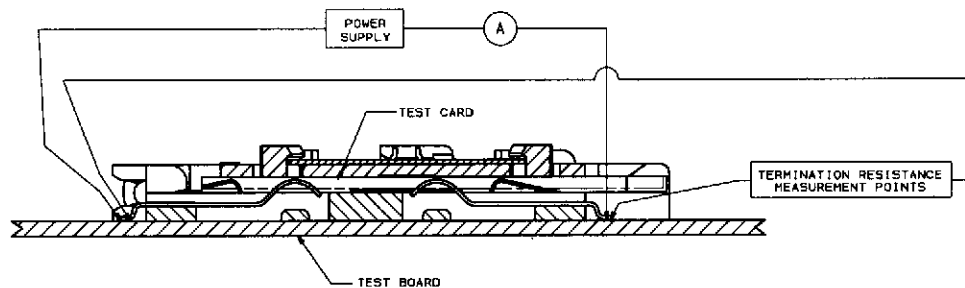


Figure 3
Termination Resistance Measurement Points

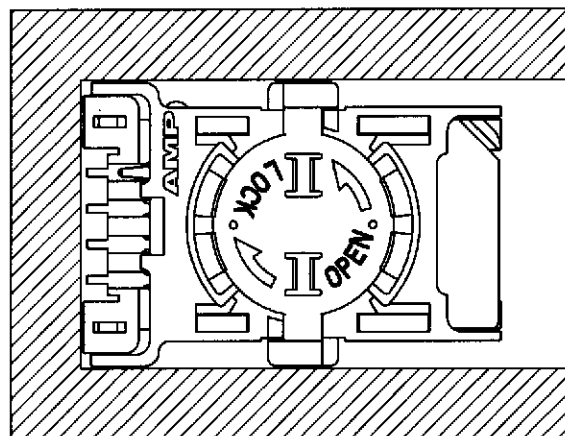
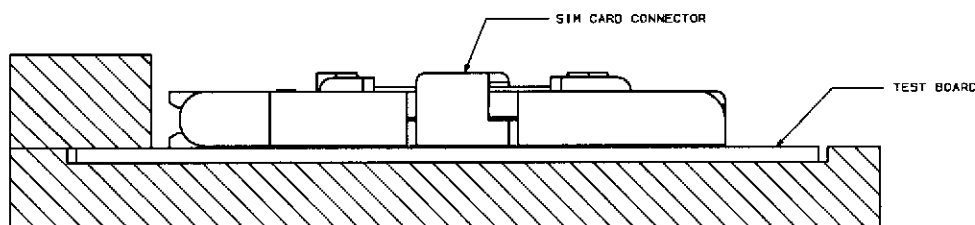


Figure 4
Vibration & Mechanical Shock Mounting Fixture

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